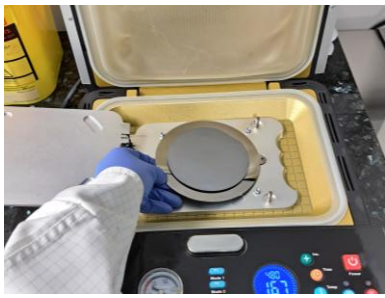
IBEC
Institute for Bioengineering of Catalonia

Core Facilities

MicroFabSpace

Manufacturer
Eden Tech

Model
Sublym 100



Hot Embossing

Hot embossing

Equipment used for the replication of 3D-moulds by applying temperature and pressure. This process significantly reduces polymer replication time from original moulds and can be performed to obtain different thermoformable-polymer replicas, such as Flexdym (PDMS like polymer), PMMA and others. By this, we can replicate molds made of epoxy-resins, glass, and silicon wafers.

Technical specifications

- Temperature range: 50 °C – 180 °C.
- Temperature ramp: 180 °C / 5min.
- Maximum mould size: 4 inches.
- Maximum height mould: 1 cm.
- Washers and spacers to adjust height: 0.1 mm, 0.2 mm, 0.3 mm, 0.5 mm, 1 mm-5mm, 6 mm, 8 mm, 10 mm, 12 mm.
- Vacuum reached (0.6-0.8 bar), allows applying forces between 1.2kN-1.8kN.
- Pre-heating process: till 120s (2min).
- Maximum process time: till 999s.
- Memory for 2 processes.